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**2007:**  
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**Lecturers:** Avram Bar-Chen, H. Anthony Chan, Paul Franzon, George Harman, R. Wayne Johnson, Badih El-Kareh, George Katopis, John H. Lau, Michael Leby, Michael Pecht, Lue Martens, James E. Morris, T. Paul Parker, Karl Puttlitz, John M. Segelken, Ephraim Suhir, Paul Totta, Walter Trybula, Rao Tummala, Paul Wesling, C.P. Wong, and Ralph W. Wyndrum, Jr.

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Refer to [www.cpmt.org](http://www.cpmt.org) for CPMT Society Chapters and Student Branches list

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### 2008/09 Deadlines for Submitting Articles:

February 25<sup>th</sup>, 2009      May 25<sup>th</sup>, 2009  
August 25<sup>th</sup>, 2009      November 25<sup>th</sup>, 2008

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